



- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

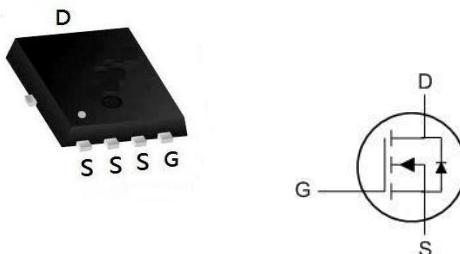
Product Summary

BVDSS	RDS(ON)	ID
30V	7.0mΩ	50A

Description

The XXW50N03D is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications. The XXW50N03D meet the RoHS and Green

PRPAK3X3 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	50	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	A
I _{DM}	Pulsed Drain Current ²	120	A
EAS	Single Pulse Avalanche Energy ³	39	mJ
I _{AS}	Avalanche Current	50	A
P _D @T _C =25°C	Total Power Dissipation ⁴	18	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	75	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	4.32	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.027	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_D=12\text{A}$	---	7	8.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	---	10	14	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.0	---	2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-5.8	---	$\text{mV}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1.7	---	Ω
Q_g	Total Gate Charge (4.5V)	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=12\text{A}$	---	12.8	---	nC
Q_{gs}	Gate-Source Charge		---	3.3	---	
Q_{gd}	Gate-Drain Charge		---	6.5	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=12\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$	---	4.5	---	ns
T_r	Rise Time		---	10.8	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	25.5	---	
T_f	Fall Time		---	9.6	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1200	---	pF
C_{oss}	Output Capacitance		---	163	---	
C_{rss}	Reverse Transfer Capacitance		---	131	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,6}	$V_G=V_D=0\text{V}$, Force Current	---	---	50	A
I_{SM}	Pulsed Source Current ^{2,6}		---	---	120	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=34\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

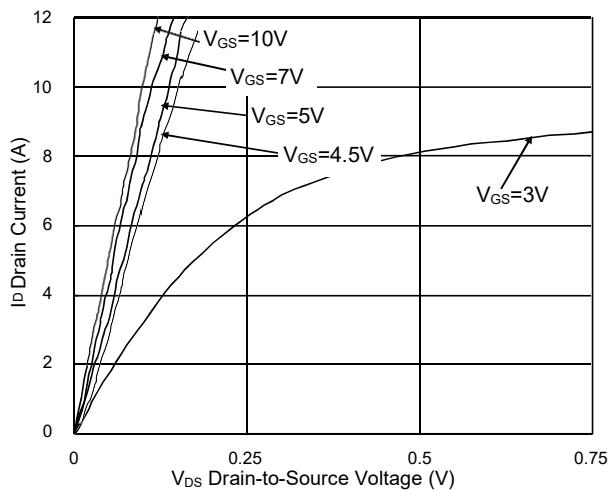


Fig.1 Typical Output Characteristics

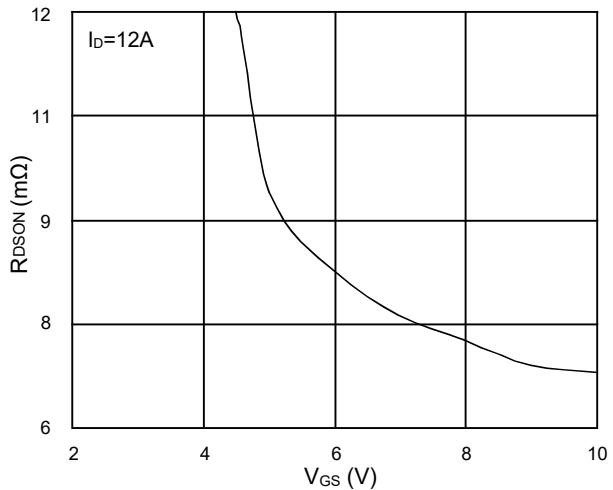


Fig.2 On-Resistance vs. G-S Voltage

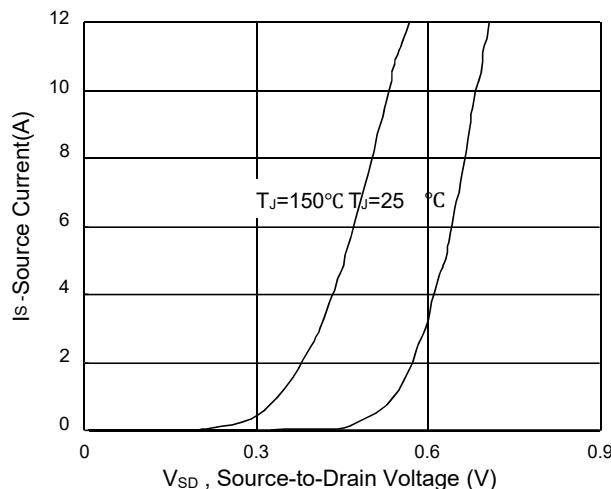


Fig.3 Forward Characteristics of Reverse

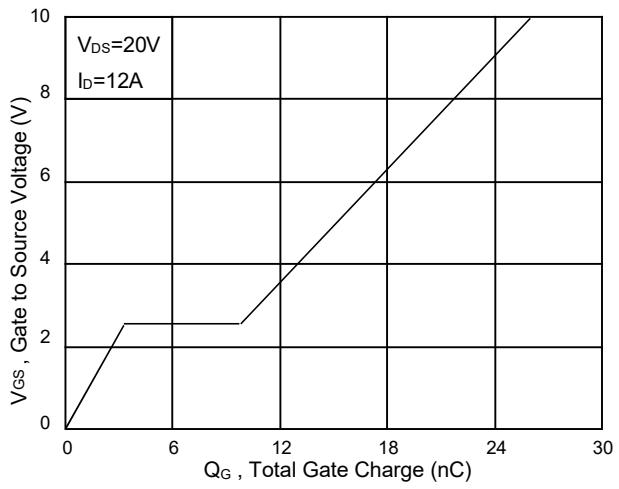


Fig.4 Gate-Charge Characteristics

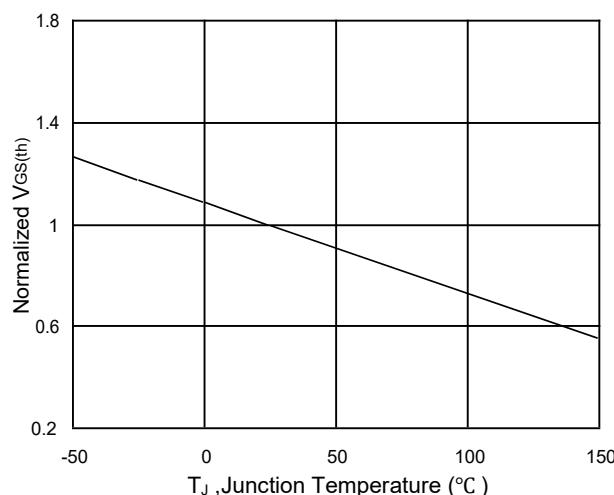


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

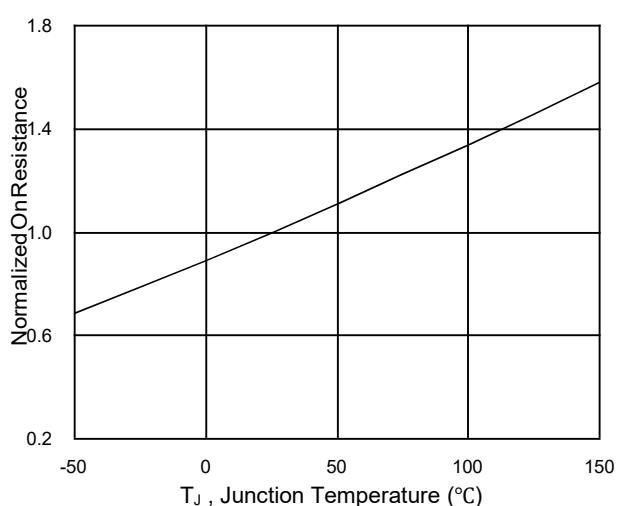
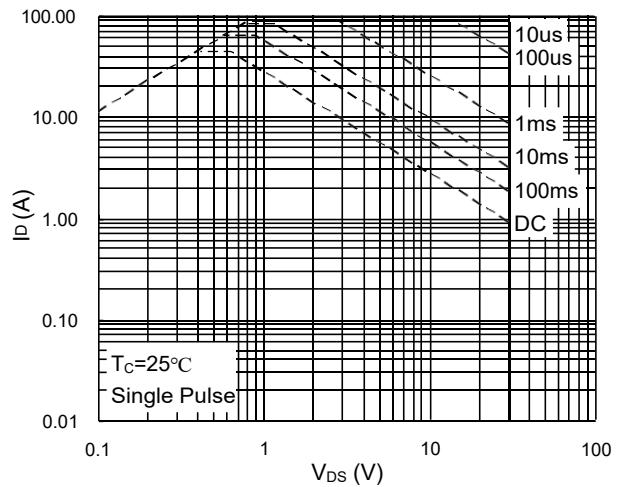
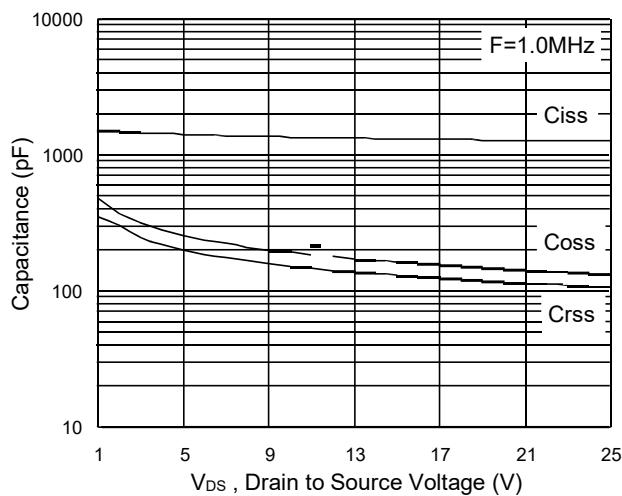
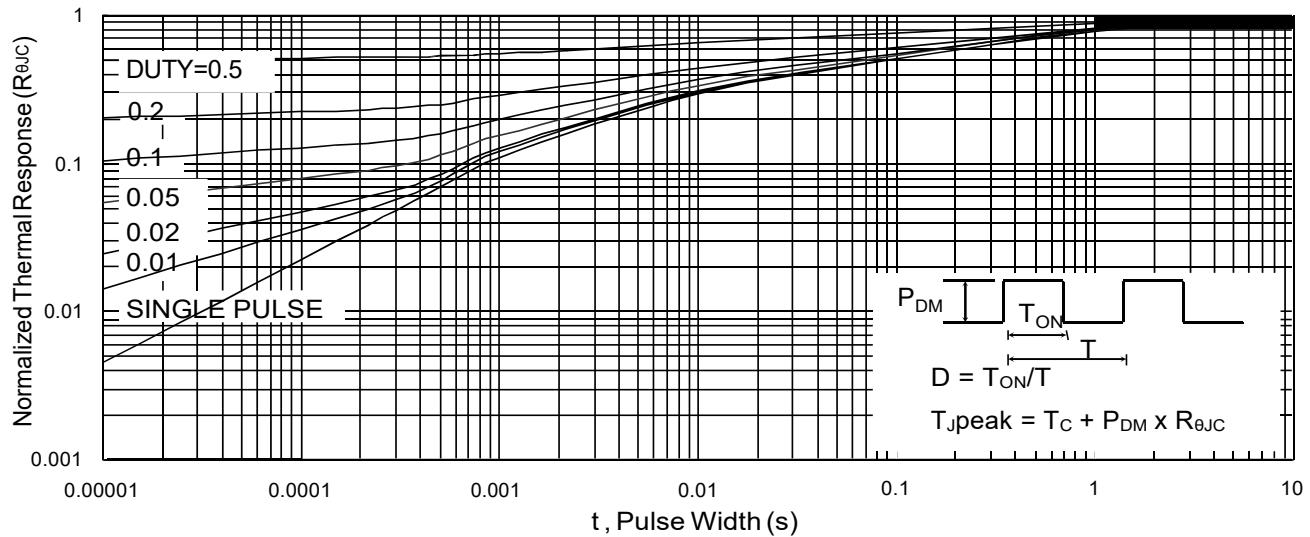
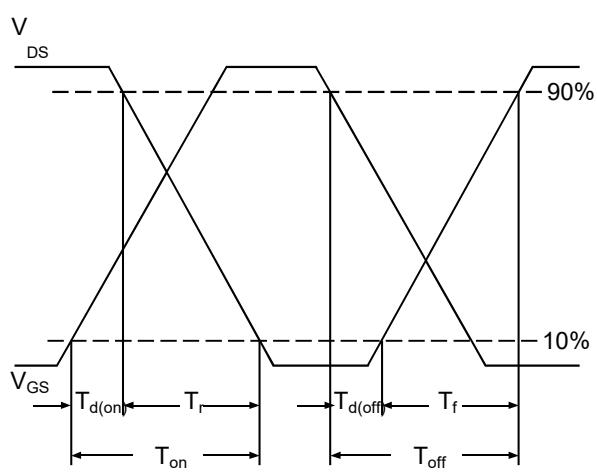
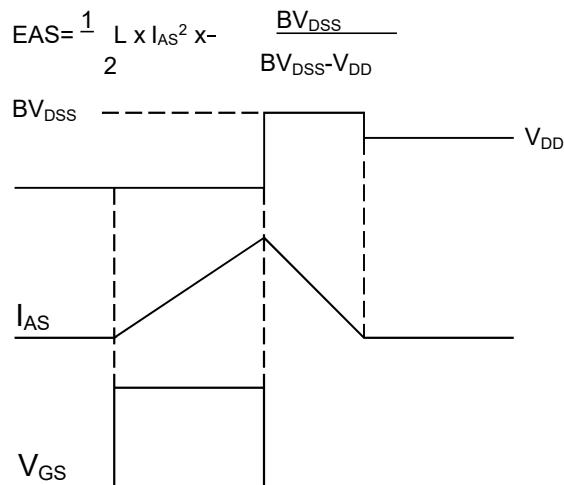
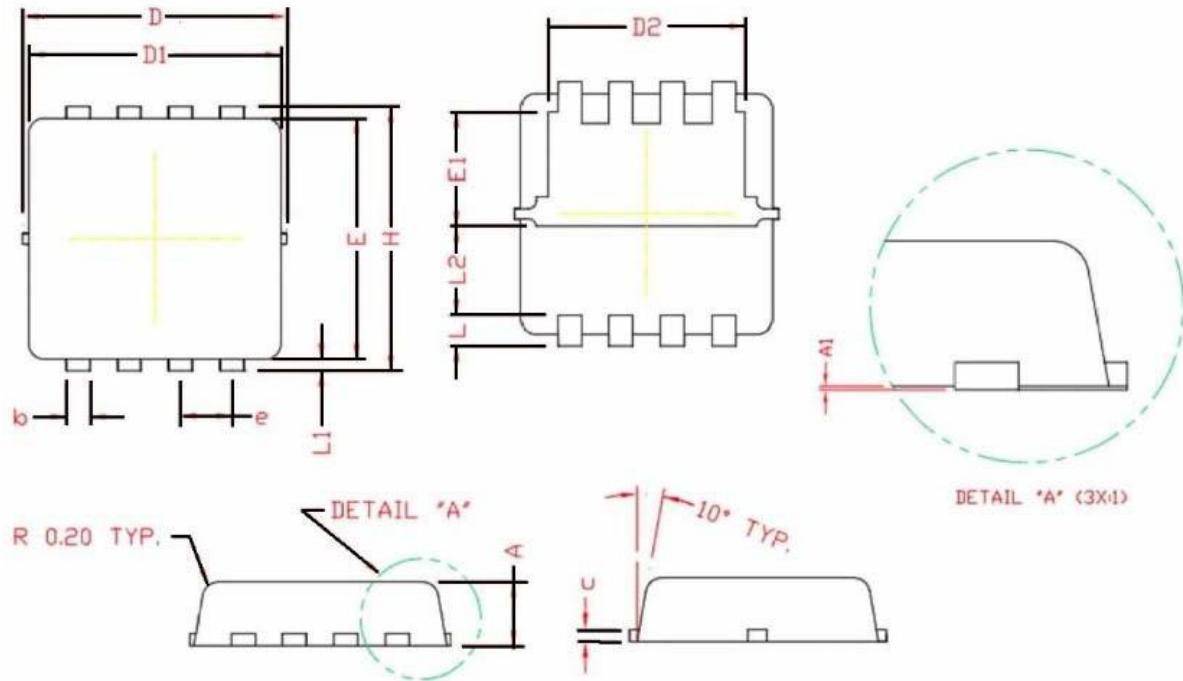


Fig.6 Normalized R_{DSON} vs. T_J


Fig.7 Capacitance
Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform

PDFN3333-8L Package Information

COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.70	0.80	0.90
A1	0.00	0.03	0.05
b	0.24	0.30	0.35
c	0.10	0.15	0.20
D	3.25	3.32	3.40
D1	3.05	3.15	3.25
D2	2.40	2.50	2.60
E	3.00	3.10	3.20
E1	1.35	1.45	1.55
e	0.65 BSC.		
H	3.20	3.30	3.40
L	0.30	0.40	0.50
L1	0.10	0.15	0.20
L2	1.13 REF.		